



Minutes of P-2.2 Subcommittee on Aluminum, Film & Mica Capacitors

Monday April 24, 2006, Sheraton Yankee Trader Hotel, Fort Lauderdale, Florida

P-2.2 Committee's Scope:

Aluminum electrolytic, paper, film, and mica capacitors for all AC and DC applications, except inductive heating and utility power-factor correction.

Attendees:

| NAME | COMPANY |
|----------------|-----------------------|
| Mike Lauri | IBM |
| Carl Lindquist | San-O Industrial Corp |
| Laird Macomber | Cornell Dubilier |
| Ed Mikoski | EIA/ECA |
| Jayson Young | KEMET |

| <u>Member Organizations Present</u> | <u>Present at this meeting</u> | <u>Present at Fall 2005 meeting?</u> | <u>Present Spring 2005 Mtg?</u> |
|--|---------------------------------------|---|--|
| Cornell Dubilier | Y | Y | Y |
| IBM | Y | Y | Y |
| KEMET | Y | Y | Y |

^Indicates activated as member of committee

| <u>Member Organizations Absent</u> | <u>Present at This Meeting?</u> | <u>Present at Fall 2005 meeting?</u> | <u>Present Spring 2005 Mtg?</u> |
|---|--|---|--|
| AVX | N | Y | N |
| Panasonic | N | Y | Y |

* Indicates not used in determination of quorum due to record of non-attendance

| <u>Other Organizations Present</u> |
|---|
| EIA/ECA |
| San-O Industrial Corp |

1.0 Call to Order

Chairman Laird Macomber called the meeting to order at 11:30 A.M.

2.0 Committee Organization and Procedures

Laird was acting Secretary in Terry Charles' absence.

2.1 Membership and Attendance

The roster was circulated and a quorum was present

2.2 Approval of Agenda

The Agenda was unanimously approved.

2.3 Approval of October 17, 2005 Subcommittee Meeting Minutes

The minutes were unanimously approved.

2.4 Correspondence

There was no correspondence

2.5 Review of the Committee's scope

The scope was unanimously accepted unchanged.

3.0 Reports

There were no reports.

4.0 Old Business

4.1 Status of SMT Film Chip Specification

SMT Film Chip Specification has been assigned PN-5140. The members of the Task group remain as before, Chris Reynolds, Terry Charles and Laird Macomber. Plan to use RS-376 Fixed Film Dielectric Capacitors in Metallic and Non-Metallic Cases for DC application as a guide for this SMT spec. Terry Charles is the chairman of this subcommittee. Companies to include on the conference calls are AVX, Cornell Dubilier, Kemet, Panasonic, and Vishay.

4.2 Results of ballot for SP-4283 (EIA 797), Aluminum Electrolytic Capacitor Application Guideline

The voting period expired on June 27, 2005. Laird emailed Cecelia requesting vote results on the ballot.

4.3 Results of Ballot for SP 4985 (ANSI/EIA/ECA-956), Aluminum Electrolytic Chip Capacitor with Polymer Cathode

The voting period expired on July 5, 2005. Laird emailed Cecelia requesting vote results on the ballot.

4.4 Results of Ballot for SP 4984 (ANSI/EIA/ECA-955), Surface Mount Aluminum Electrolytic Chip Capacitor with Polymer Cathode Qualification Specification

Mike Lauri said that in response to the ballot sent by Cecelia on April 28, 2005 he had returned these comments: In Section 1.3 we should delete the reference to 57G9271 IBM Preconditioning Specification, and in Table 1, Method 4.8, Thermal Shock we should add double asterisks (**) to indicate that three lots minimum are to be tested. This change makes the test method consistent with 4.4, 4.5, 4.6 and 4.7. The subcommittee unanimously agreed to these changes. Get ballot results from Cecelia.

The voting period expired on July 5, 2005. Laird emailed Cecelia asking the result of the ballot.

4.5 Five-year Review of Documents

At the May 16, 2005 meeting we had agreed to archive the following documents:

EIA-376 Fixed Film Dielectric Capacitors in Metallic and Non-Metallic Cases, EIA 71, REAF 11/90

EIA-395 Polarized Aluminum Electrolytic Capacitors, EIA 70, REAF 10/82

EIA-479 A Film-Paper, Film Dielectric Capacitors for 50/60 Hz Voltage Doubler Power Supplies, EIA 5/93, ANSI 3/93

RS-361 Feed-Through Radio Interference Capacitors, Paper, Film, and Paper/Film Dielectric, EIA 1/69, ANSI 8/69

RS377 Metallized Dielectric Capacitors in Metallic and Non-Metallic, EIA 70, REAF 11/90

RS377-1 Parts List Supplement to RS-377, EIA 70, REAF 02/90

And we agreed to review the following documents:

EIA-495-A Film Dielectric Capacitors with Metallized Paper Electrodes for AC Applications, EIA 1/90, ANSI 11/89 REAF 5/97

EIA580A000 Sectional Specification for Fixed Chip Capacitors with Metallized Electrodes and Polyethylene-Terephthalate Dielectric for Use in Electronic Equipment, EIA 1/92, ANSI 11/91

EIA-580A0AC Detail Specification for Fixed Metallized Polyethylene Terephthalate Film Dielectric, EIA 6/98

EIA-580A0AC Detail Specification for Fixed Metallized Polyethylene Terephthalate Film Dielectric DC Capacitors Axial Leaded, EIA 6/98, ANSI 5/98

EIA-580AA00 Blank Detail Specification: Fixed Metallized Polyethylene-Terephthalate Film Chip Capacitors for DC – Encapsulated

EIA-580BA00 Blank Detail Specification: Fixed Metallized Electrode Film Dielectric AC Capacitors, EIA 10/97, ANSI 8/97

EIA-815 Miniature Aluminum Electrolytic Capacitor (Leaded) Qualification Specification, EIA 8/99

RS376 Fixed Film Dielectric Capacitors in Metallic and Non-Metallic Cases for DC Application, EIA 3/76, ANSI 7/71

RS376-1 Parts List Supplement to RS-376, Fixed Film Dielectric Capacitors in Metallic and Non-Metallic Cases for DC Application, EIA 11/71, ANSI 9/72, EIA REAF 1990

RS401 Paper, Paper/Film, Film Dielectric Capacitors for Power Semiconductor Applications, EIA 3/73 RS454 Fixed Paper & Film-Paper Dielectric Capacitor, EIA 78, REAF 8/90

We agreed that IS749 would be affirmed as an EIA ANSI standard.

5.0 Next Meeting

Monday, 25 September 2006,
Silver Legacy Resort
407 Virginia Street
Reno, NV 89505

6.0 Adjournment

The meeting was adjourned at approximately 13:00.

This meeting was conducted in accordance with the EIA Legal Guidelines and the Manual of Organization and Procedures.

Laird Macomber
Chairman

